

L Number	Hits	Search Text	DB	Time stamp
1	11012	contaminant near3 removal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 07:48
3	55	contaminant near3 removal near12 film and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 07:49
4	17	contaminant near3 removal near12 film and polymer and 134/.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 07:49
2	200	contaminant near3 removal near12 film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:02
5	4	contaminant near3 removal near12 film and aircraft	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 07:52
6	413	contaminant near3 removal near12 (film layer coat\$3) and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:05
7	25	contaminant near3 removal near12 (film layer coat\$3) and clean\$3 and decontamination	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:03
8	7277	contaminant and particle near12 (film layer coat\$3) and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:06
9	631	contaminant and particle near12 (film layer coat\$3) and clean\$3 and 134/.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:06
10	18	contaminant and particle near12 (film layer coat\$3) and clean\$3 and 134/.cccls. and cure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:07
11	301	contaminant and particle near12 (film layer coat\$3) and clean\$3 and 134/.cccls. and cur\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:49
12	0	military and decontamination and biological and polymer and cure and 134/.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:50
13	5	military and decontamination and biological and polymer and cure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:51
14	2272	adhesive near3 remov\$3 and particle and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 08:52

15	110	adhesive near3 remov\$3 and particle and clean\$3 and (military aircraft) .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:16
16	0	adhesive near3 remov\$3 and particle and clean\$3 and military and aircraft and biological	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:16
17	0	adhesive near3 remov\$3 and particle and military and aircraft and biological	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:17
18	2	adhesive near3 remov\$3 and particle and military and aircraft and toxic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:17
19	19	coat\$3 and remov\$3 and particle and military and aircraft and toxic and cure and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:19
20	81	coat\$3 and remov\$3 and particle and military and aircraft and toxic and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:20
21	11517	coat\$3 and encapsulat\$5 and toxic and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:20
22	303	coat\$3 and particle near1 encapsulat\$5 and toxic and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:21
23	208	coat\$3 and particle near1 encapsulat\$5 and toxic and polymer	USPAT	2004/01/12 09:23
24	146	coat\$3 and particle near1 encapsulat\$5 and toxic and polymer not seed not sperm not hydrogel	USPAT	2004/01/12 09:28
25	135	coat\$3 and particle near1 encapsulat\$5 and toxic and polymer not seed not sperm not hydrogel not toner	USPAT	2004/01/12 09:24
26	3460	particl\$6 near3 encapsulat\$5 not seed not sperm not hydrogel not dental	USPAT	2004/01/12 09:30
27	3010	particl\$6 near3 encapsulat\$5 not seed not sperm not hydrogel not dental not biological	USPAT	2004/01/12 09:30
28	2948	particl\$6 near3 encapsulat\$5 not seed not sperm not hydrogel not dental not biolog\$5	USPAT	2004/01/12 09:30
29	67	particl\$6 near3 encapsulat\$5.ti. not seed not sperm not hydrogel not dental not biolog\$5	USPAT	2004/01/12 09:31
30	52	particl\$6 near3 encapsulat\$5.ti. not seed not sperm not hydrogel not dental not biolog\$5 not enzym\$6	USPAT	2004/01/12 09:31
31	0	particl\$6 near3 encapsulat\$5.ti. not seed not sperm not hydrogel not dental not biolog\$5 not enzym\$6 and wafer	USPAT	2004/01/12 09:32
32	96	particl\$6 near3 encapsulat\$5 not seed not sperm not hydrogel not dental not biolog\$5 not enzym\$6 and wafer	USPAT	2004/01/12 09:32
33	74	particl\$6 near3 encapsulat\$5 not seed not sperm not hydrogel not dental not biolog\$5 not enzym\$6 and wafer not ink	USPAT	2004/01/12 09:35
34	3	encapsulation.ti. and 134/.ccls.	USPAT	2004/01/12 09:36
35	1		USPAT	2004/01/12 09:36

36	1		USPAT	2004/01/12 09:36
38	1		USPAT	2004/01/12 09:37
39	1		USPAT	2004/01/12 09:37
40	1		USPAT	2004/01/12 09:37
42	1		USPAT	2004/01/12 09:37
43	1		USPAT	2004/01/12 09:38
46	82	(134/1.3, 134/184 , 134/201 , 134/4 , 134/902).ccls. and encapsulat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/12 09:41
49	1		USPAT	2004/01/12 09:45
50	1		USPAT	2004/01/12 09:45
51	1		USPAT	2004/01/12 09:46
52	1		USPAT	2004/01/12 09:47
54	1		USPAT	2004/01/12 09:50
55	1		USPAT	2004/01/12 09:50
56	1		USPAT	2004/01/12 09:51
57	1		USPAT	2004/01/12 09:51
58	1		USPAT	2004/01/12 09:51
59	1		USPAT	2004/01/12 09:52
60	1		USPAT	2004/01/12 09:53
61	1		USPAT	2004/01/12 09:54
-	4	gale.in. & kern.in. & syverson.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/31 07:32
-	6	((("6036785") or ("5451295") or ("4491484"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/17 16:42
-	1	"63-155729"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/17 16:45
-	1	63-155729	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/17 16:45
-	20	"155729"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/17 16:47
-	1	"freeze water around foreign matter"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/17 16:48
-	6	((("6036785") or ("5451295") or ("4491484"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/25 16:05
-	3	((("6036785") or ("5451295") or ("4491484"))).PN.	USPAT	2003/03/25 16:05
-	2	("5451295").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/28 14:24
-	1	"4119483".PN.	USPAT	2003/03/28 14:22
-	1	"4448636".PN.	USPAT	2003/03/28 14:22
-	1	"4519872".PN.	USPAT	2003/03/28 14:22
-	1	"4586980".PN.	USPAT	2003/03/28 14:22
-	1	"5275689".PN.	USPAT	2003/03/28 14:22
-	1	("4491484").PN.	USPAT	2003/03/28 14:24

-	30	"4491484"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 14:24
-	3	wafer and "4491484"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 14:26
-	30	"4491484"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 14:56
-	12	ultrasonic near10 (frozen ice) near22 removal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 15:02
-	2	("5724186").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:03
-	1	"5475530".PN.	USPAT	2003/03/28 15:02
-	1	"5076854".PN.	USPAT	2003/03/28 15:03
-	9	cryogenic near3 clean\$3 and dioxide and ice and (sonic ultrasonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:08
-	1	cryogenic near3 clean\$3 and dioxide and (frozen ice) near12 layer and (sonic ultrasonic) near22 remov\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:10
-	3	cryogenic near3 clean\$3 and (frozen ice) near4 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:13
-	1125	clean\$3 and (frozen ice) near4 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:13
-	214	cryogenic and (frozen ice) near4 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:15
-	46	cryogenic and (frozen ice) near4 layer and (substrate wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/28 16:17
-	2	(("6095776") or ("6206636")).PN.	USPAT	2003/03/31 07:40
-	2	(("6095776") or ("6206636")).PN.	USPAT	2003/03/31 07:41
-	6	(("4666283") or ("6095776") or ("6206636")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 07:41
-	3	(("4666283") or ("6095776") or ("6206636")).PN.	USPAT	2003/03/31 08:02
-	4	(("4666283") or ("6095776") or ("6206636") or ("6116855")).PN.	USPAT	2003/03/31 08:02

-	2	("5724186").PN.	USPAT; US-PGPOB; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 11:13
-	1	"4491484".PN.	USPAT	2003/08/14 10:12
-	1	"4883775".PN.	USPAT	2003/08/14 10:13